

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Jen 12-07-04

Applicant(s): Martin R. Handforth

Application No.: 09/821722

Filed: 3/29/2001

Title: Signal Layer Interconnects

Attorney Docket No.: 13888R0US02U 120-042

Group Art Unit:  
2827

Conf. No. 4607

Examiner:  
NorrisCommissioner for Patents  
P.O. Box 1450  
Arlington, VA 22313-1450RECEIVED  
CENTRAL FAX CENTER  
NOV 19 2004RESPONSE AFTER FINAL

Dear Sir:

Please enter the following Amendment and Remarks in response to the Final Office

Action of September 21, 2004.

**CLAIMS**

1. (currently amended) An interconnection device comprising:

first and second outer layers, each including substrate material; and

at least one inner layer disposed between said first and second outer layers, said inner layer including at least one conductive signal trace disposed on a rigid substrate material proximate to an edge of the interconnection device and being accessible for direct electrical connection with a corresponding exposed signal trace, wherein at least one conductive protrusion is formed on said conductive inner layer trace.